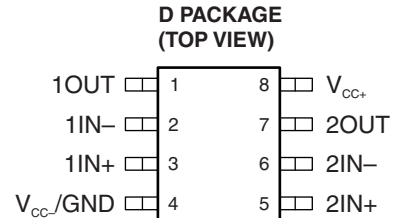


HIGH-SLEW-RATE SINGLE-SUPPLY OPERATIONAL AMPLIFIER

FEATURES

- Qualified for Automotive Applications
- Wide Gain-Bandwidth Product: 4 MHz
- High Slew Rate: 13 V/ μ s
- Fast Settling Time: 1.1 μ s to 0.1%
- Wide-Range Single-Supply Operation: 4 V to 36 V
- Wide Input Common-Mode Range Includes Ground (V_{CC-})
- Low Total Harmonic Distortion: 0.02%
- Large-Capacitance Drive Capability: 10,000 pF
- Output Short-Circuit Protection



DESCRIPTION/ORDERING INFORMATION

Quality, low-cost, bipolar fabrication with innovative design concepts is employed for the TL3472 operational amplifier. This device offers 4 MHz of gain-bandwidth product, 13-V/ μ s slew rate, and fast settling time, without the use of JFET device technology. Although the TL3472 can be operated from split supplies, it is particularly suited for single-supply operation because the common-mode input voltage range includes ground potential (V_{CC-}). With a Darlington transistor input stage, this device exhibits high input resistance, low input offset voltage, and high gain. The all-npn output stage, characterized by no dead-band crossover distortion and large output voltage swing, provides high-capacitance drive capability, excellent phase and gain margins, low open-loop high-frequency output impedance, and symmetrical source/sink ac frequency response. This low-cost amplifier is an alternative to the MC33072 and the MC34072 operational amplifiers.

ORDERING INFORMATION⁽¹⁾

T_A	PACKAGE ⁽²⁾		ORDERABLE PART NUMBER	TOP-SIDE MARKING
-40°C to 125°C	SOIC – D	Reel of 2500	TL3472QDRQ1	T3472Q

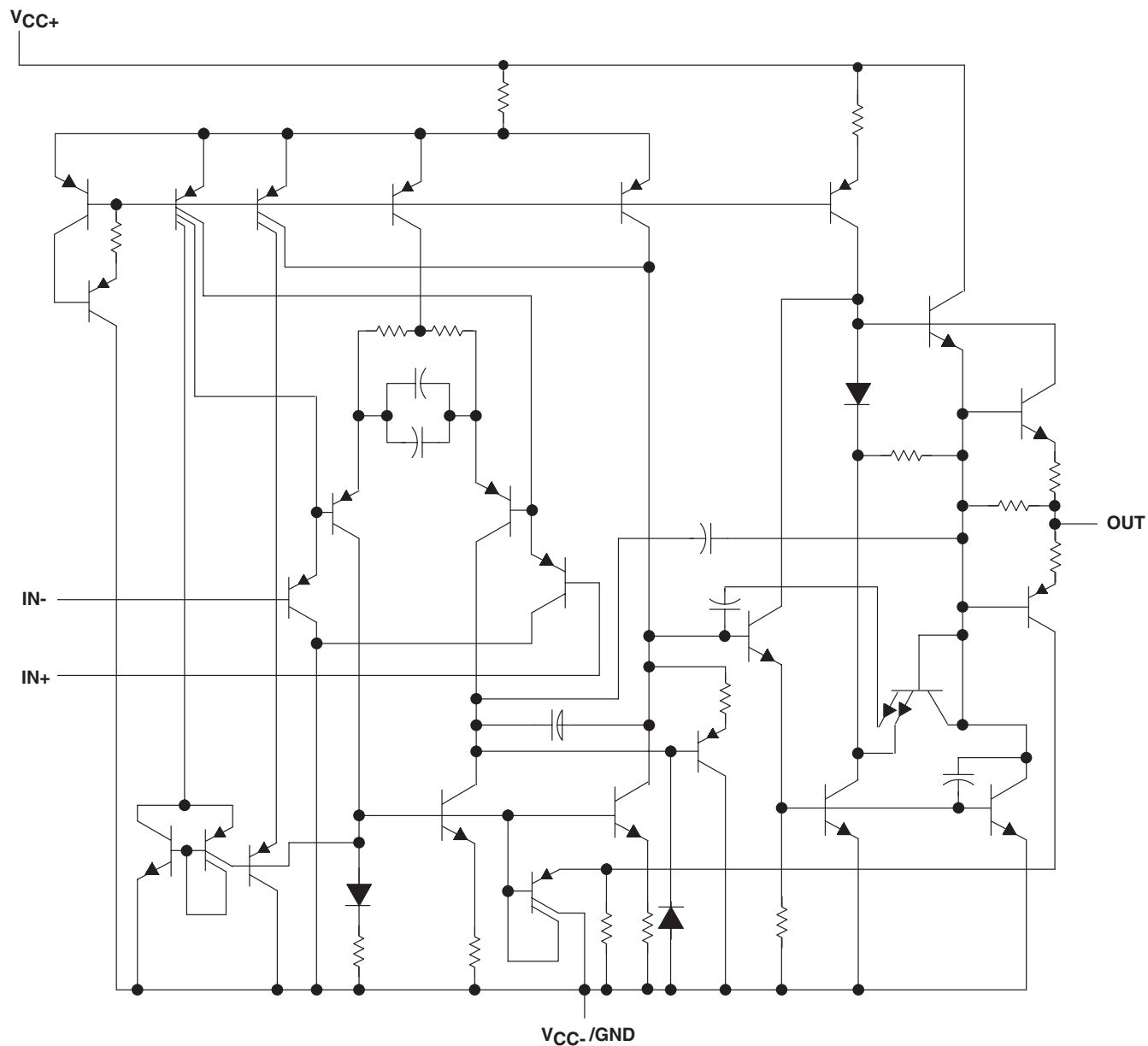
(1) For the most current package and ordering information, see the Package Option Addendum at the end of this document, or see the TI web site at www.ti.com.

(2) Package drawings, thermal data, and symbolization are available at www.ti.com/packaging.



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SCHEMATIC (EACH AMPLIFIER)



ABSOLUTE MAXIMUM RATINGS⁽¹⁾

over operating free-air temperature range (unless otherwise noted)

V_{CC+}	Supply voltage ⁽²⁾	18 V
V_{CC-}		–18 V
V_{ID}	Differential input voltage	± 36 V
V_I	Input voltage (any input)	$V_{CC\pm}$
I_I	Input current (each input)	± 1 mA
I_O	Output current	± 80 mA
	Total current into V_{CC+}	80 mA
	Total current out of V_{CC-}	80 mA
	Duration of short-circuit current at (or below) 25°C ⁽³⁾	Unlimited
θ_{JA}	Package thermal impedance ⁽⁴⁾⁽⁵⁾	97°C/W
T_J	Operating virtual junction temperature	150°C
	Lead temperature 1.6 mm (1/16 inch) from case for 10 seconds	260°C
T_{stg}	Storage temperature range	–65°C to 150°C

- (1) Stresses beyond those listed under *absolute maximum ratings* may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under *recommended operating conditions* is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.
- (2) All voltage values, except differential voltages, are with respect to the midpoint between V_{CC+} and V_{CC-} .
- (3) The output can be shorted to either supply. Temperature and/or supply voltages must be limited to ensure that the maximum dissipation rating is not exceeded.
- (4) Maximum power dissipation is a function of $T_J(\text{max})$, θ_{JA} , and T_A . The maximum allowable power dissipation at any allowable ambient temperature is $P_D = (T_J(\text{max}) - T_A)/\theta_{JA}$. Operating at the absolute maximum T_J of 150°C can impact reliability.
- (5) The package thermal impedance is calculated in accordance with JESD 51-7.

RECOMMENDED OPERATING CONDITIONS

		MIN	MAX	UNIT	
$V_{CC\pm}$	Supply voltage	4	36	V	
V_{IC}	Common-mode input voltage	$V_{CC} = 5$ V	0	2.8	V
		$V_{CC\pm} = \pm 15$ V	–15	12.8	
T_A	Operating free-air temperature	–40	125	°C	

ELECTRICAL CHARACTERISTICSat specified free-air temperature, $V_{CC\pm} = \pm 15\text{ V}$ (unless otherwise noted)

PARAMETER		TEST CONDITIONS		$T_A^{(1)}$	MIN	TYP ⁽²⁾	MAX	UNIT
V_{IO}	Input offset voltage	$V_{IC} = 0, V_O = 0, R_S = 50\ \Omega$	$V_{CC} = 5\text{ V}$	25°C	1.5	16	mV	
			$V_{CC} = \pm 15\text{ V}$	25°C	1	17		
				Full range				22
α_{VIO}	Temperature coefficient of input offset voltage	$V_{IC} = 0, V_O = 0, R_S = 50\ \Omega$	$V_{CC} = \pm 15\text{ V}$	Full range	10		$\mu\text{V}/^\circ\text{C}$	
I_{IO}	Input offset current	$V_{IC} = 0, V_O = 0, R_S = 50\ \Omega$	$V_{CC} = \pm 15\text{ V}$	25°C	6	75	nA	
				Full range				300
I_{IB}	Input bias current	$V_{IC} = 0, V_O = 0, R_S = 50\ \Omega$	$V_{CC} = \pm 15\text{ V}$	25°C	100	500	nA	
				Full range				700
V_{ICR}	Common-mode input voltage range	$R_S = 50\ \Omega$		25°C	-15 to 12.8		V	
				Full range				-15 to 12.8
V_{OH}	High-level output voltage	$V_{CC+} = 5\text{ V}, V_{CC-} = 0, R_L = 2\text{ k}\Omega$		25°C	3.7	4	V	
				25°C	13.6	14		
				Full range	13.4			
V_{OL}	Low-level output voltage	$V_{CC+} = 5\text{ V}, V_{CC-} = 0, R_L = 2\text{ k}\Omega$		25°C	0.1	0.3	V	
				25°C	-14.7	-14.3		
				Full range				-13.5
A_{VD}	Large-signal differential voltage amplification	$V_O = \pm 10\text{ V}, R_L = 2\text{ k}\Omega$		25°C	25	100	V/mV	
				Full range	20			
I_{OS}	Short-circuit output current	Source: $V_{ID} = 1\text{ V}, V_O = 0$		25°C	-10	-34	mA	
		Sink: $V_{ID} = -1\text{ V}, V_O = 0$			20	27		
CMRR	Common-mode rejection ratio	$V_{IC} = V_{ICR}(\text{min}), R_S = 50\ \Omega$		25°C	65	97	dB	
k_{SVR}	Supply-voltage rejection ratio ($\Delta V_{CC\pm}/\Delta V_{IO}$)	$V_{CC\pm} = \pm 13.5\text{ V to } \pm 16.5\text{ V}, R_S = 100\ \Omega$		25°C	70	97	dB	
I_{CC}	Supply current (per channel)	$V_O = 0, \text{ No load}$		25°C	3.5	4.5	mA	
				Full range	4.5	5.5		
				25°C	3.5	4.5		

(1) Full range $T_A = -40^\circ\text{C}$ to 125°C (2) All typical values are at $T_A = 25^\circ\text{C}$.

OPERATING CHARACTERISTICS
 $V_{CC\pm} = \pm 15\text{ V}$, $T_A = 25^\circ\text{C}$

PARAMETER		TEST CONDITIONS		MIN	TYP	MAX	UNIT
SR+	Positive slew rate	$V_I = -10\text{ V to } 10\text{ V}$, $R_L = 2\text{ k}\Omega$, $C_L = 300\text{ pF}$	$A_V = 1$	8	10		V/ μs
SR–	Negative slew rate	$V_I = -10\text{ V to } 10\text{ V}$, $R_L = 2\text{ k}\Omega$, $C_L = 300\text{ pF}$	$A_V = -1$		13		V/ μs
t_s	Settling time	$A_{VD} = -1$, 10-V step	$T_O 0.1\%$		1.1		μs
			$T_O 0.01\%$		2.2		
V_n	Equivalent input noise voltage	$f = 1\text{ kHz}$, $R_S = 100\ \Omega$			49		nV/ $\sqrt{\text{Hz}}$
I_n	Equivalent input noise current	$f = 1\text{ kHz}$			0.22		pA/ $\sqrt{\text{Hz}}$
THD	Total harmonic distortion	$V_{O(PP)} = 2\text{ V to } 20\text{ V}$, $R_L = 2\text{ k}\Omega$, $A_{VD} = 10$, $f = 10\text{ kHz}$			0.02		%
GBW	Gain-bandwidth product	$f = 100\text{ kHz}$		3	4		MHz
BW	Power bandwidth	$V_{O(PP)} = 20\text{ V}$, $R_L = 2\text{ k}\Omega$, $A_{VD} = 1$, THD = 5.0%			160		kHz
ϕ_m	Phase margin	$R_L = 2\text{ k}\Omega$	$C_L = 0$		70		deg
			$C_L = 300\text{ pF}$		50		
	Gain margin	$R_L = 2\text{ k}\Omega$	$C_L = 0$		12		dB
			$C_L = 300\text{ pF}$		4		
r_i	Differential input resistance	$V_{IC} = 0$			150		M Ω
C_i	Input capacitance	$V_{IC} = 0$			2.5		pF
	Channel separation	$f = 10\text{ kHz}$			101		dB
z_o	Open-loop output impedance	$f = 1\text{ MHz}$, $A_V = 1$			20		Ω

D (R-PDSO-G8)

PLASTIC SMALL OUTLINE



D (R-PDSO-G8)

PLASTIC SMALL OUTLINE



- NOTES:
- A. All linear dimensions are in millimeters.
 - B. This drawing is subject to change without notice.
 - C. Publication IPC-7351 is recommended for alternate designs.
 - D. Laser cutting apertures with trapezoidal walls and also rounding corners will offer better paste release. Customers should contact their board assembly site for stencil design recommendations. Refer to IPC-7525 for other stencil recommendations.
 - E. Customers should contact their board fabrication site for solder mask tolerances between and around signal pads.

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